

AMENDMENTS TO THE SPECIFICATION

Amend the specification as follows:

At page 4, the first complete paragraph:

With the second conventional technique, the motherboard 149 is arranged in the chassis 104 so as to be parallel to the top surface (or bottom surface) of the chassis 104. Accordingly, the cooling airflow is parallel to the motherboard 149. Thus, the second conventional technique can solve the above problems of the first conventional technique. However, with the second conventional technique, the circuit board 102 is moved up and down to connect and separate the circuit board 102 to and from the motherboard connector 152, respectively. Thus, it is difficult to connect and separate the circuit board 102 to and from the motherboard connector 152 unless there is a sufficient clearance between the circuit board 102 and the top surface 124 of the chassis 104. This problem is particularly severe when the size of the chassis ~~102~~104 is reduced.

At page 5, the first paragraph:

However, since the size of the chassis ~~102~~ 104 is reduced, it is difficult to connect and separate the circuit board 102 to and from the motherboard 149 when the clearance between the circuit board 102 and the top surface 124 of the chassis ~~102~~ 104 is less than 1 3/8 inches.

At page 9, the first complete paragraph:

The electronic circuit packages 12 and 13 are arranged substantially parallel to each other. The connectors 14-1, arranged on the electronic package 12 are provided parallel to and

opposite the connector 14-2, arranged on the electronic circuit package 13. Accordingly, the connectors 14-1, arranged on the ~~electronic circuit package~~ electronic circuit 12, are each connected to a ZIF connector 15-1 provided on the top side of a corresponding electronic circuit package 11. The connectors 14-2, arranged on the electronic circuit package 13, are each connected to a ZIF connector 15-2 provided on the bottom side of the corresponding electronic circuit package 11.

At page 17, the first complete paragraph

This embodiment differs from the third embodiment in that the electronic circuit packages 41 can be mounted in the housing through either end of the electronic circuit package 42. The ZIF connectors 43-2 are ~~connected~~ arranged -adjacent to the ZIF connectors 43-1 on the electronic circuit package 42. More specifically, the ZIF connectors 43-2 are arranged in an area adjacent to a short side of the ZIF connectors 43-1. The ZIF connectors 43-1 and 43-2 may be arranged in overlapping areas. In this case, the ZIF connectors 43-1 and 43-2 are arranged alternately in a staggered format.

At page 21, the first complete paragraph

If a connector is present on both opposite electronic circuit packages (for example, ~~electronic circuit packages 11 and 12~~ electronic circuit packages 12 and 13) as in the case of the first, second, and fifth embodiments, the electronic circuit package 61 has the terminal 65 at both edge portions of the electronic circuit package 61.

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At page 22, the first complete paragraph

If a connector is present on both opposite electronic circuit packages (for example, ~~electronic circuit packages 11 and 12~~) electronic circuit packages 12 and 13 as in the case of the first, second, and fifth embodiments, the electronic circuit package 61 has a terminal 66 at both edge portions of the electronic circuit package 61.

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AMENDMENTS TO THE DRAWINGS

Figure 1 and Figure 6 have been amended to correct typographical errors.

Attachment: Replacement Sheets (Figure 1 and Figure 6)